

Title (en)
NICOCRALY-ALLOY, A POWDER, A COATING AND A COMPONENT

Title (de)
NICOCRALY-LEGIERUNG, PULVER, BESCHICHTUNG UND KOMPONENTE

Title (fr)
ALLIAGE DE NICOCRALY, POUDRE, REVÊTEMENT ET COMPOSANT

Publication
EP 3985137 A1 20220420 (EN)

Application
EP 20201694 A 20201014

Priority
EP 20201694 A 20201014

Abstract (en)
The invention comprises a Nickel-based alloy, and least comprising (in wt%): 25.7 % - 27.3% Cobalt (Co), 15.0% - 16.0% Chromium (Cr), 12.2% - 13.2% Aluminum (Al), 0.3% - 0.5% Yttrium (Y), 2.5% - 3.5% Ruthenium (Ru), 0.4% - 0.8% Silicon (Si), 0.4% - 0.6% Tantalum (Ta), 0.4% - 0.6% Molybdenum (Mo).

IPC 8 full level
C22C 19/05 (2006.01); **C23C 30/00** (2006.01)

CPC (source: EP US)
B22F 1/10 (2022.01 - US); **B22F 1/12** (2022.01 - US); **C22C 19/056** (2013.01 - EP US); **C22C 30/00** (2013.01 - EP); **C23C 4/06** (2013.01 - EP); **C23C 4/073** (2016.01 - EP US); **C23C 4/18** (2013.01 - EP); **C23C 28/00** (2013.01 - EP); **C23C 28/3215** (2013.01 - EP US); **C23C 28/345** (2013.01 - EP); **C23C 28/3455** (2013.01 - EP); **C23C 30/00** (2013.01 - EP); **B22F 2301/15** (2013.01 - US); **B22F 2999/00** (2013.01 - US)

Citation (applicant)

- NIJDAM TJSLOOF WG., ACTA MATERIALIA, vol. 55, 2007, pages 5980
- SMIALEK J, JAYNE D, SCHAEFFER J, MURPHY W., THIN SOLID FILMS, vol. 253, 1994, pages 285
- SMIALEK J.: "Metallurgical Transactions A", PHYSICAL METALLURGY AND MATERIALS SCIENCE, vol. 22A, 1991, pages 739

Citation (search report)

- [XA] WO 2013056935 A1 20130425 - SIEMENS AG [DE]
- [XA] EP 2423439 A2 20120229 - HONEYWELL INT INC [US]
- [XA] WO 0075398 A1 20001214 - ABB RESEARCH LTD [CH], et al
- [A] EP 2256221 A1 20101201 - MITSUBISHI HEAVY IND LTD [JP]

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

DOCDB simple family (publication)
EP 3985137 A1 20220420; CN 116324035 A 20230623; EP 4196620 A1 20230621; US 2023366066 A1 20231116;
WO 2022078733 A1 20220421

DOCDB simple family (application)
EP 20201694 A 20201014; CN 202180069346 A 20210924; EP 2021076386 W 20210924; EP 21786784 A 20210924;
US 202118029907 A 20210924